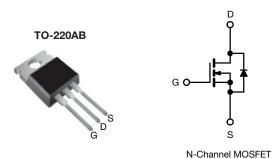
HALOGEN FREE



Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	100			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.16		
Q _g max. (nC)	26			
Q _{gs} (nC)	5.5			
Q _{gd} (nC)	11			
Configuration	Single			

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF530PbF
Lead (Pb)-free and halogen-free	IRF530PbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise parameter			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	100	- V	
Gate-source voltage			V _{GS}	± 20		
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C		14		
		$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	10	А	
Pulsed drain current ^a			I _{DM}	56		
Linear derating factor				0.59	W/°C	
Single pulse avalanche energy ^b			E _{AS}	69	mJ	
Repetitive avalanche current a			I _{AR}	14	А	
Repetitive avalanche energy ^a			E _{AR}	8.8	mJ	
Maximum power dissipation	T _C =	25 °C	P _D	88	W	
Peak diode recovery dV/dt ^c			dV/dt	5.5	V/ns	
Operating junction and storage temperature range	rating junction and storage temperature range			-55 to +175	00	
Soldering recommendations (peak temperature) ^d	For 10 s			300	°C	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N · m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 528 μ H, R_g = 25 Ω , I_{AS} = 14 A (see fig. 12)
- c. $I_{SD} \le 14 \text{ A}$, $dI/dt \le 140 \text{ A/}\mu\text{s}$, $V_{DD} \le V_{DS}$, $T_J \le 175 \text{ °C}$
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	62	
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	1.7	

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static						•	,
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0$	100	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.12	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0	-	4.0	V
Gate-source leakage	I _{GSS}	V _G	V _{GS} = ± 20 V		-	± 100	nA
Zoro gata valtaga drain aurrent	1	V _{DS} = 100 V, V _{GS} = 0 V		-	-	25	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 80 V, V ₀	_{GS} = 0 V, T _J = 150 °C	-	-	250	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 8.4 A ^b	-	-	0.16	Ω
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 8.4 A ^b		5.1	-	-	S
Dynamic							
Input capacitance	C _{iss}	V	-	670	-	pF	
Output capacitance	C _{oss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	250		-
Reverse transfer capacitance	C_{rss}			-	60	-	
Total gate charge	Q_g			-	-	26	nC
Gate-source charge	Q_{gs}	V _{GS} = 10 V	$I_D = 14 \text{ A}, V_{DS} = 80 \text{ V},$ see fig. 6 and 13 b	-	-	5.5	
Gate-drain charge	Q_{gd}			-	-	11	
Turn-on delay time	t _{d(on)}	V_{DD} = 50 V, I_{D} = 14 A R_{g} = 12 Ω , R_{D} = 3.6 Ω , see fig. 10 ^b		-	10	-	- ns
Rise time	t _r			-	34	-	
Turn-off delay time	t _{d(off)}			-	23	-	
Fall time	t _f			-	24	-	
Gate input resistance	R_g	f = 1 MHz, open drain		1.0	-	4.7	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	الم
Internal source inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	14	A
Pulsed diode forward current ^a	I _{SM}			-	-	56	
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 14 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	2.5	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 14 A, dl/dt = 100 A/µs b		-	150	280	ns
Body diode reverse recovery charge	Q _{rr}			-	0.85	1.7	μC
Forward turn-on time	t _{on}	Intrinsic turn-	-on is do	minated b	y L _S and	L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 μ s; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

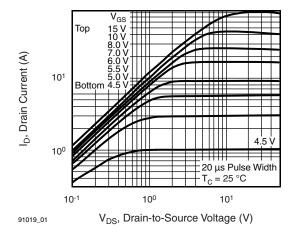


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

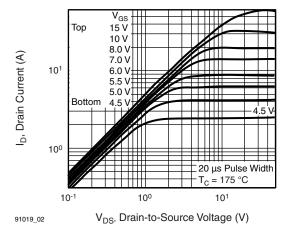


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

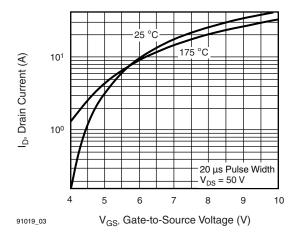


Fig. 3 - Typical Transfer Characteristics

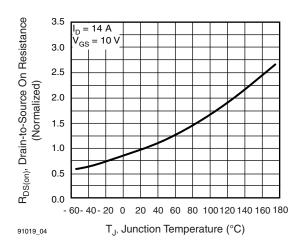


Fig. 4 - Normalized On-Resistance vs. Temperature

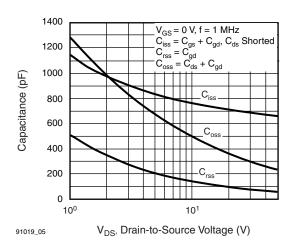


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

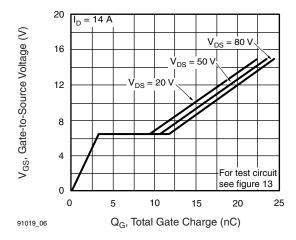


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



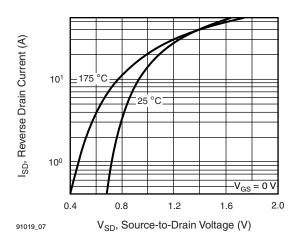


Fig. 7 - Typical Source-Drain Diode Forward Voltage

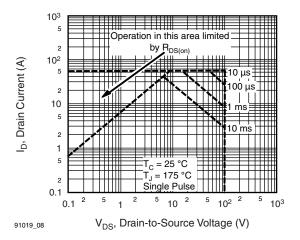


Fig. 8 - Maximum Safe Operating Area

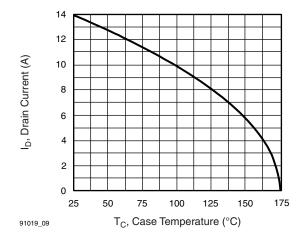


Fig. 9 - Maximum Drain Current vs. Case Temperature

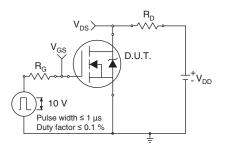


Fig. 10a - Switching Time Test Circuit

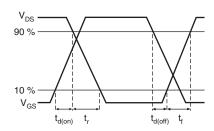


Fig. 10b - Switching Time Waveforms



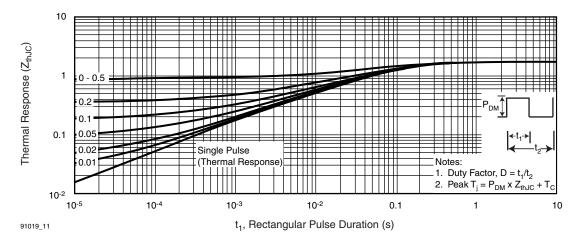


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

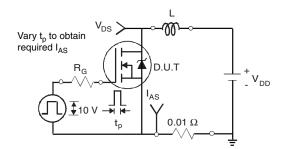


Fig. 12a - Unclamped Inductive Test Circuit

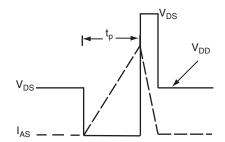


Fig. 12b - Unclamped Inductive Waveforms

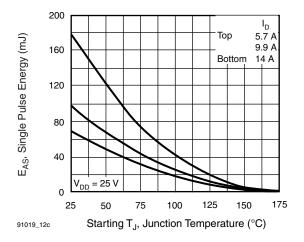


Fig. 12c - Maximum Avalanche Energy vs. Drain Current



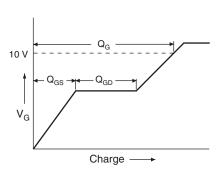


Fig. 13a - Basic Gate Charge Waveform

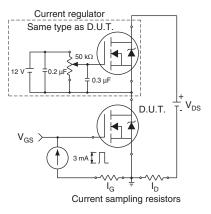
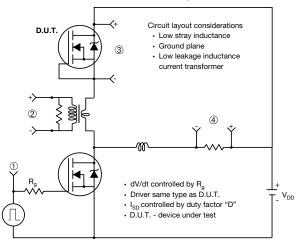


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



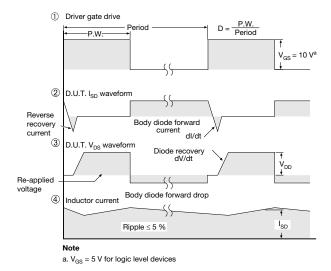


Fig. 14 - For N-Channel

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